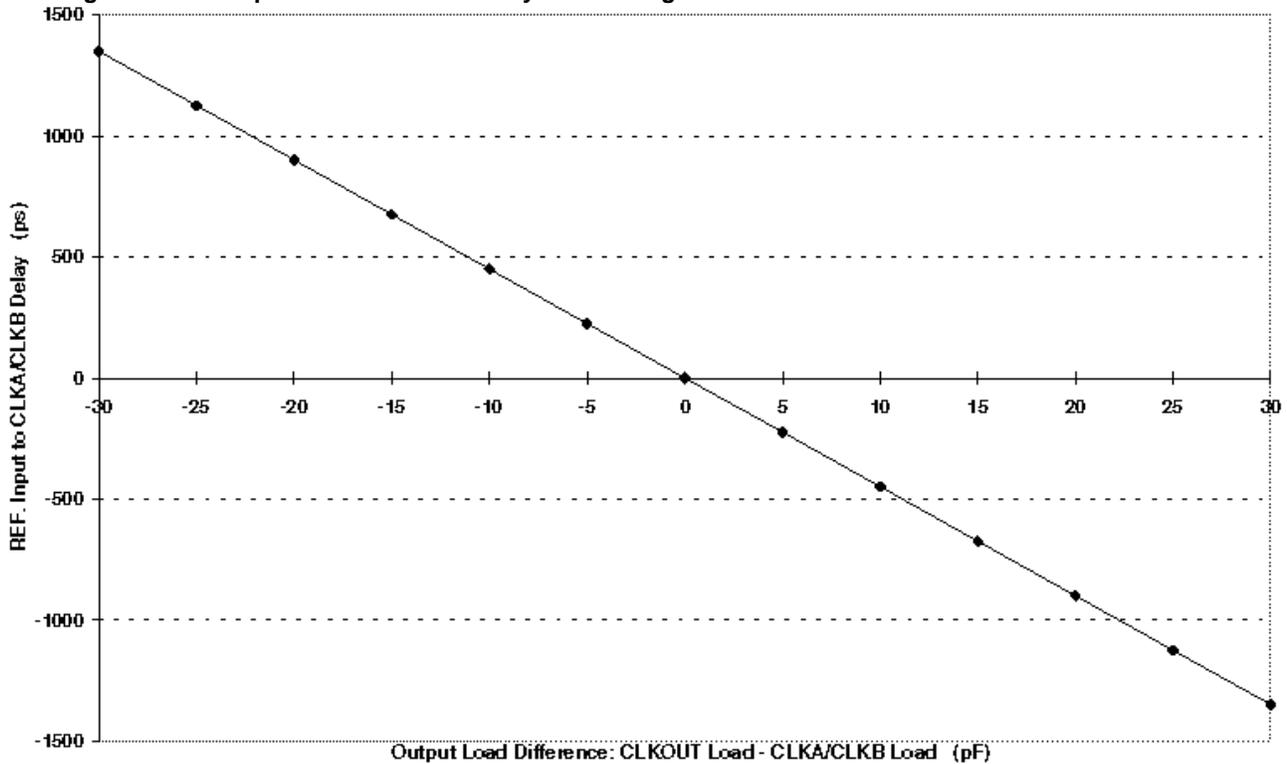


Select Input Decoding for CY23S09

S2	S1	CLOCK A1–A4	CLOCK B1–B4	CLKOUT ^[1]	Output Source	PLL Shutdown
0	0	Three-state	Three-state	Driven	PLL	N
0	1	Driven	Three-state	Driven	PLL	N
1	0	Driven	Driven	Driven	Reference	Y
1	1	Driven	Driven	Driven	PLL	N

Figure 1. REF. Input to CLKA/CLKB Delay vs. Loading Difference between CLKOUT and CLKA/CLKB Pins



Zero Delay and Skew Control

All outputs must be uniformly loaded to achieve Zero Delay between the input and output. Because the CLKOUT pin is the internal feedback to the PLL, its relative loading can adjust the input-output delay. This is shown in the above graph.

For applications requiring zero input-output delay, all outputs, including CLKOUT, must be equally loaded. Even if CLKOUT is not used, it must have a capacitive load equal to that on other outputs, to obtain zero input-output delay. If input to output delay adjustments are required, use the above graph to calculate loading differences between the CLKOUT pin and other outputs.

For zero output-output skew, be sure to load all outputs equally. For further information, see application note “AN1234 - CY2308: Zero Delay Buffer.”

Spread Aware

Many systems being designed now use a technology called Spread Spectrum Frequency Timing Generation. Cypress is one of the pioneers of SSFTG development and designed this product so as not to filter off the Spread Spectrum feature of the Reference input, assuming it exists. When a zero delay buffer is not designed to pass the SS feature through, the result is a significant amount of tracking skew, which may cause problems in systems requiring synchronization.

For more details on Spread Spectrum timing technology, please see the Cypress Whitepaper [EMI and Spread Spectrum Technology](#).

Note

1. This output is driven and has an internal feedback for the PLL. The load on this output can be adjusted to change the skew between the reference and output.

Pinouts

Figure 2. Pin Configuration – CY23S09

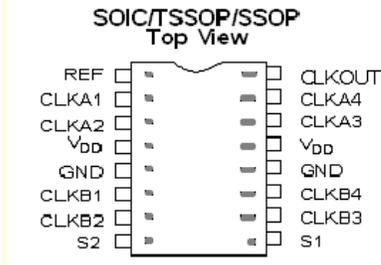


Figure 3. Pin Configuration – CY23S05

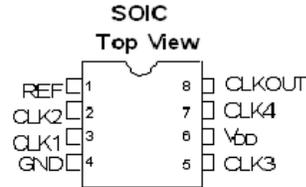


Table 1. Pin Description for CY23S09

Pin	Signal	Description
1	REF ^[2]	Input reference frequency, 5 V tolerant input
2	CLKA1 ^[3]	Buffered clock output, bank A
3	CLKA2 ^[3]	Buffered clock output, bank A
4	V _{DD}	3.3 V supply
5	GND	Ground
6	CLKB1 ^[3]	Buffered clock output, bank B
7	CLKB2 ^[3]	Buffered clock output, bank B
8	S2 ^[4]	Select input, bit 2
9	S1 ^[4]	Select input, bit 1
10	CLKB3 ^[3]	Buffered clock output, bank B
11	CLKB4 ^[3]	Buffered clock output, bank B
12	GND	Ground
13	V _{DD}	3.3 V supply
14	CLKA3 ^[3]	Buffered clock output, bank A
15	CLKA4 ^[3]	Buffered clock output, bank A
16	CLKOUT ^[3]	Buffered output, internal feedback on this pin

Table 2. Pin Description for CY23S05

Pin	Signal	Description
1	REF ^[2]	Input reference frequency, 5 V tolerant input
2	CLK2 ^[3]	Buffered clock output
3	CLK1 ^[3]	Buffered clock output
4	GND	Ground
5	CLK3 ^[3]	Buffered clock output
6	V _{DD}	3.3 V supply
7	CLK4 ^[3]	Buffered clock output
8	CLKOUT ^[3]	Buffered clock output, internal feedback on this pin

Notes

- 2. Weak pull down.
- 3. Weak pull down on all outputs.
- 4. Weak pull up on these inputs.

Maximum Ratings

Supply voltage to ground potential	-0.5 V to +7.0 V	Maximum soldering temperature (10 seconds)	260 °C
DC input voltage (Except REF)	-0.5 V to $V_{DD} + 0.5$ V	Junction temperature.....	150 °C
DC input voltage REF	-0.5 V to 7 V	Static discharge voltage	
Storage temperature	-65 °C to +150 °C	(per MIL-STD-883, Method 3015)	> 2,000 V

Operating Conditions for CY23S05SC-XX and CY23S09SC-XX Commercial Temperature Devices^[5]

Parameter	Description	Min	Max	Unit
V_{DD}	Supply voltage	3.0	3.6	V
T_A	Operating temperature (Ambient temperature)	0	70	°C
C_L	Load capacitance, below 100 MHz		30	pF
C_L	Load capacitance, from 100 MHz to 133 MHz		10	pF
C_{IN}	Input capacitance		7	pF

Electrical Characteristics for CY23S05SC-XX and CY23S09SC-XX Commercial Temperature Devices

Parameter	Description	Test Conditions	Min	Max	Unit
V_{IL}	Input LOW voltage ^[6]			0.8	V
V_{IH}	Input HIGH voltage ^[6]		2.0		V
I_{IL}	Input LOW current	$V_{IN} = 0$ V		50.0	μA
I_{IH}	Input HIGH current	$V_{IN} = V_{DD}$		100.0	μA
V_{OL}	Output LOW voltage ^[7]	$I_{OL} = 8$ mA (-1) $I_{OH} = 12$ mA (-1H)		0.4	V
V_{OH}	Output HIGH voltage ^[7]	$I_{OH} = -8$ mA (-1) $I_{OL} = -12$ mA (-1H)	2.4		V
I_{DD} (PD mode)	Power-down supply current	REF = 0 MHz		12.0	μA
I_{DD}	Supply current	Unloaded outputs at 66.67 MHz, SEL inputs at V_{DD}		32.0	mA

Switching Characteristics for CY23S05SC-1 and CY23S09SC-1 Commercial Temperature Devices^[8]

Parameter	Description	Test Conditions	Min	Typ	Max	Unit
t_1	Output frequency	30 pF load 10 pF load	10 10		100 133.33	MHz MHz
	Duty cycle ^[7] = $t_2 \div t_1$	Measured at 1.4 V, $F_{out} = 66.67$ MHz	40.0	50.0	60.0	%
t_3	Rise time ^[7]	Measured between 0.8 V and 2.0 V			2.50	ns
t_4	Fall time ^[7]	Measured between 0.8 V and 2.0 V			2.50	ns
t_5	Output-to-output skew ^[7]	All outputs equally loaded			250	ps
t_6	Delay, REF Rising Edge to CLKOUT Rising Edge ^[7]	Measured at $V_{DD}/2$		0	±350	ps
t_7	Device-to-device skew ^[7]	Measured at $V_{DD}/2$ on the CLKOUT pins of devices		0	700	ps
t_j	Cycle-to-cycle jitter ^[7]	Measured at 66.67 MHz, loaded outputs			200	ps
t_{LOCK}	PLL lock time ^[7]	Stable power supply, valid clock presented on REF pin			1.0	ms

Notes

5. Multiple Supplies: The voltage on any input or I/O pin cannot exceed the power pin during power up. Power supply sequencing is NOT required.
6. REF input has a threshold voltage of $V_{DD}/2$.
7. Parameter is guaranteed by design and characterization. Not 100% tested in production.
8. All parameters specified with loaded outputs.

Switching Characteristics for CY23S05SI-1H and CY23S09SI-1H Industrial Temperature Devices^[8]

Parameter	Description	Test Conditions	Min	Typ	Max	Unit
t1	Output frequency	30 pF load 10 pF load	10 10		100 133.33	MHz MHz
	Duty cycle ^[7] = $t_2 \div t_1$	Measured at 1.4 V, $F_{out} = 66.67$ MHz	40.0	50.0	60.0	%
	Duty cycle ^[7] = $t_2 \div t_1$	Measured at 1.4 V, $F_{out} < 50.0$ MHz	45.0	50.0	55.0	%
t3	Rise time ^[7]	Measured between 0.8 V and 2.0 V			1.50	ns
t4	Fall time ^[7]	Measured between 0.8 V and 2.0 V			1.50	ns
t5	Output-to-output skew ^[7]	All outputs equally loaded			250	ps
t6	Delay, REF Rising Edge to CLKOUT Rising Edge ^[7]	Measured at $V_{DD}/2$		0	± 350	ps
t7	Device-to-Device Skew ^[7]	Measured at $V_{DD}/2$ on the CLKOUT pins of devices		0	700	ps
t8	Output slew rate ^[7]	Measured between 0.8 V and 2.0 V using Test Circuit #2	1			V/ns
t _J	Cycle-to-cycle jitter ^[7]	Measured at 66.67 MHz, loaded outputs			200	ps
t _{LOCK}	PLL lock time ^[7]	Stable power supply, valid clock presented on REF pin			1.0	ms

Switching Waveforms

Figure 4. Duty Cycle Timing

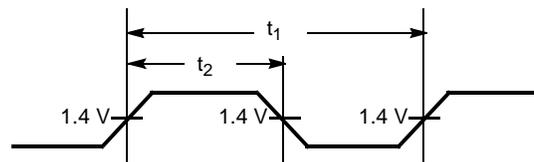


Figure 5. All Outputs Rise/Fall Time

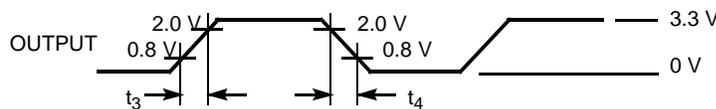


Figure 6. Output-Output Skew

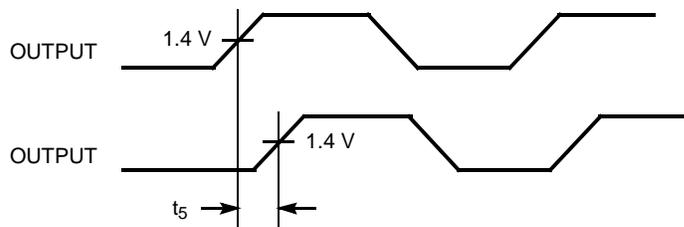
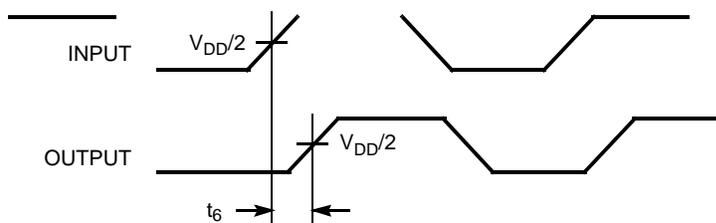
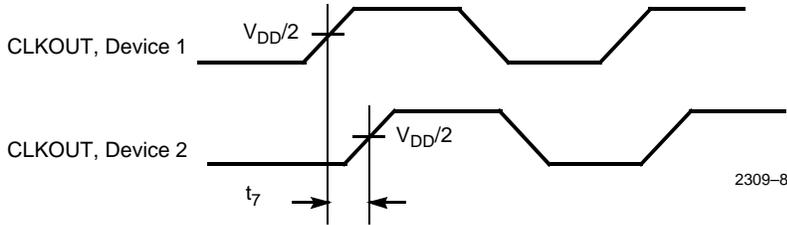


Figure 7. Input-Output Propagation Delay

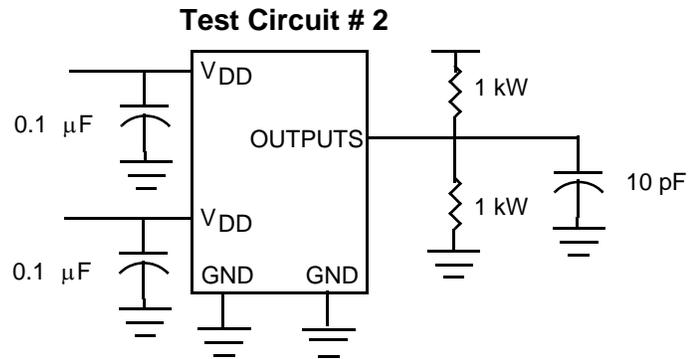
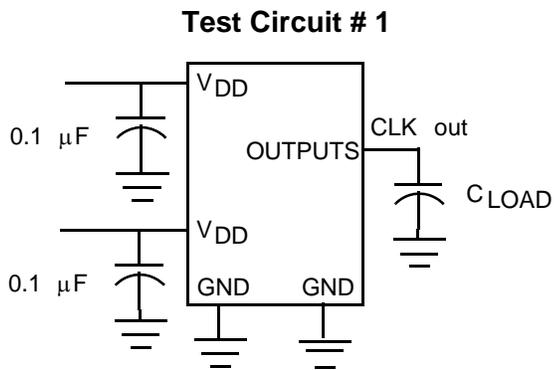


Switching Waveforms continued

Figure 8. Device-Device Skew



Test Circuits

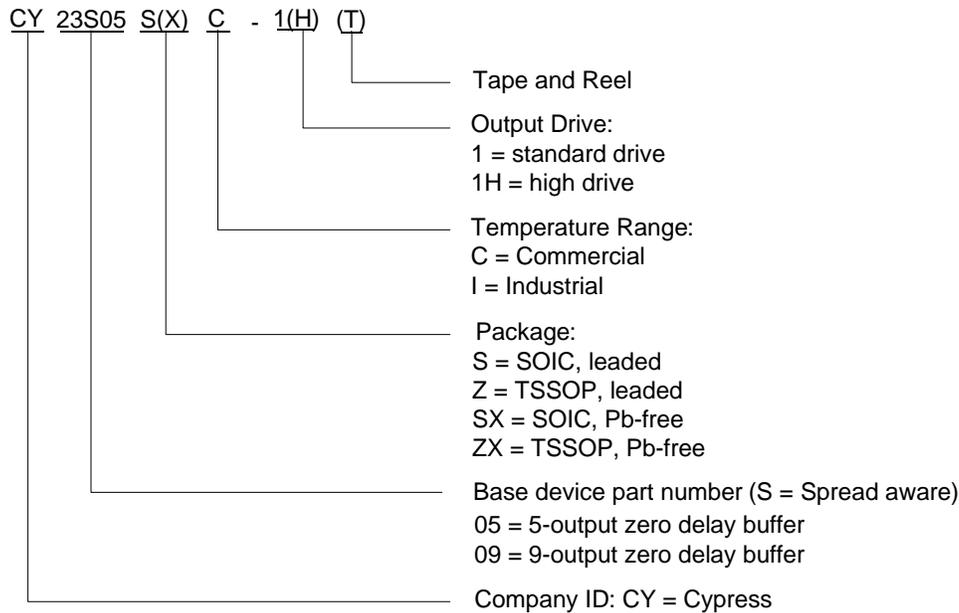


For parameter t8 (output slew rate) on -1H devices

Ordering Information

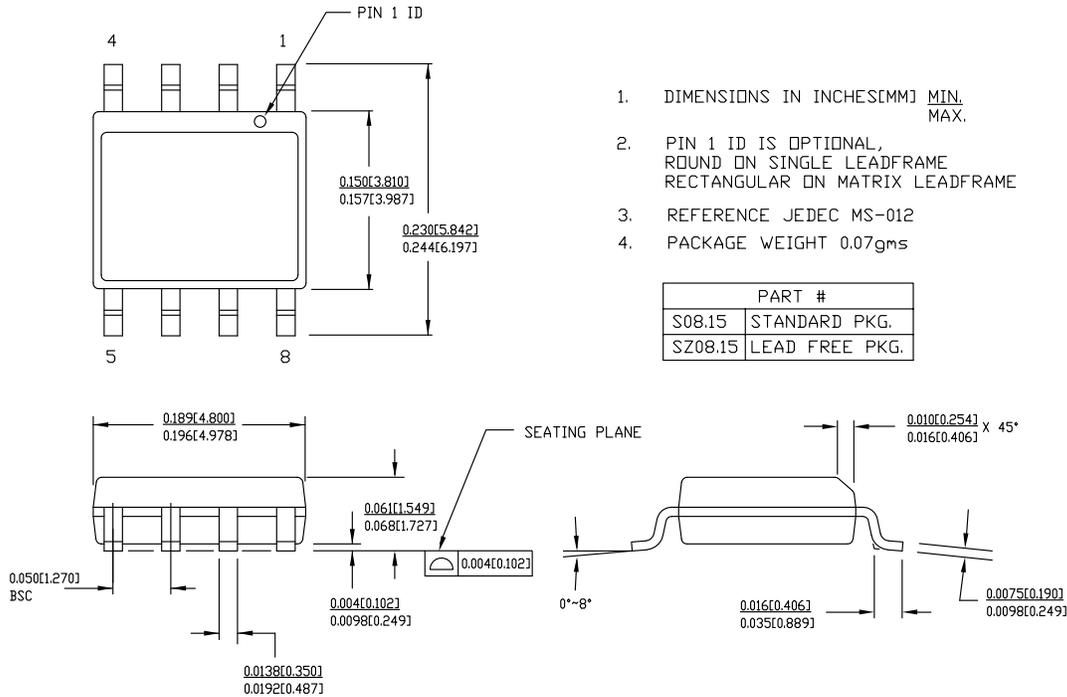
Ordering Code	Package Name	Package Type	Operating Range
Pb-Free			
CY23S05SXC-1	SZ08	8-pin 150-mil SOIC	Commercial (0 ° to 70 °C)
CY23S05SXC-1T	SZ08	8-pin 150-mil SOIC – Tape and Reel	Commercial (0 ° to 70 °C)
CY23S05SXC-1H	SZ08	8-pin 150-mil SOIC	Commercial (0 ° to 70 °C)
CY23S05SXC-1HT	SZ08	8-pin 150-mil SOIC – Tape and Reel	Commercial (0 ° to 70 °C)
CY23S05SXI-1	SZ08	8-pin 150-mil SOIC	Industrial (–40 ° to 85 °C)
CY23S05SXI-1T	SZ08	8-pin 150-mil SOIC – Tape and Reel	Industrial (–40 ° to 85 °C)
CY23S09SXC-1	SZ16	16-pin 150-mil SOIC	Commercial (0 ° to 70 °C)
CY23S09SXC-1T	SZ16	16-pin 150-mil SOIC – Tape and Reel	Commercial (0 ° to 70 °C)
CY23S09SXC-1H	SZ16	16-pin 150-mil SOIC	Commercial (0 ° to 70 °C)
CY23S09SXC-1HT	SZ16	16-pin 150-mil SOIC – Tape and Reel	Commercial (0 ° to 70 °C)
CY23S09ZXC-1H	ZZ16	16-pin 4.4 mm TSSOP	Commercial (0 ° to 70 °C)
CY23S09ZXC-1HT	ZZ16	16-pin 4.4 mm TSSOP – Tape and Reel	Commercial (0 ° to 70 °C)

Ordering Code Definitions



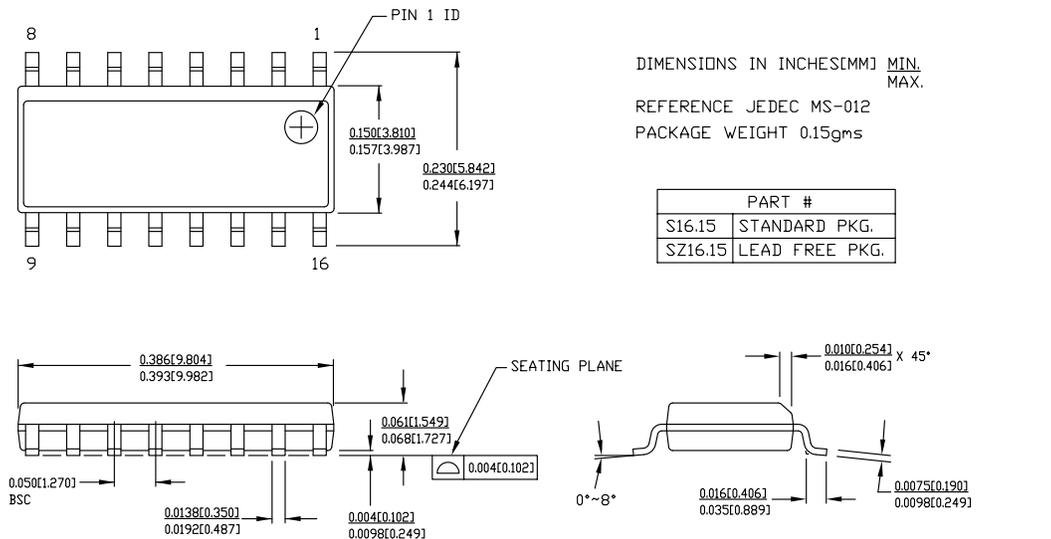
Package Diagrams

Figure 9. 8-Pin (150-Mil) SOIC S08 and SZ08



51-85066 *E

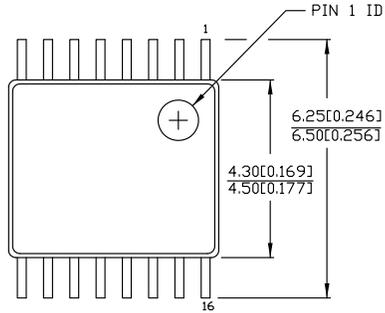
Figure 10. 16-Pin (150-Mil) SOIC S16 and SZ16



51-85068 *D

Package Diagrams continued

Figure 11. 16-Pin TSSOP 4.40 mm Body Z16 and ZZ16

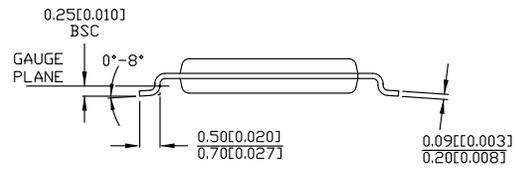
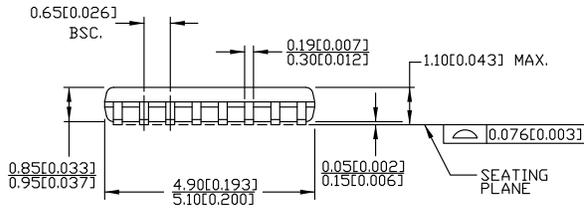


DIMENSIONS IN MM[INCHES] MIN. MAX.

REFERENCE JEDEC MO-153

PACKAGE WEIGHT 0.05gms

PART #	
Z16.173	STANDARD PKG.
ZZ16.173	LEAD FREE PKG.



51-85091 *D

Acronym

Acronym	Description
CMOS	complementary metal oxide semiconductor
EMI	electromagnetic interference
PLL	phase-locked loop
SOIC	small outline integrated circuit
SS	spread spectrum
SSFTG	spread spectrum frequency timing generator
SSOP	shrunk small outline package
TSSOP	thin shrunk small outline package

Document Conventions

Units of Measure

Symbol	Unit of Measure
°C	degree Celsius
MHZ	megahertz
uA	microamperes
mA	milliamperes
ms	milliseconds
ns	nanoseconds
%	percent
pF	picofarads
ps	picoseconds
V	volt

Document History Page

Document Title: CY23S09/CY23S05 Low Cost 3.3 V Spread Aware Zero Delay Buffer				
Document Number: 38-07296				
Rev.	ECN No.	Submission Date	Orig. of Change	Description of Change
**	111147	11/14/01	DSG	Changed from spec number 38-01094 to 38-07296
*A	111773	02/20/02	CTK	Added 150-mil SSOP option
*B	122885	12/22/02	RBI	Added power-up requirements to Operating Conditions
*C	267849	See ECN	RGL	Added Lead-Free devices
*D	2595524	10/23/08	CXQ/PYRS	Added device "Status" to Ordering Information
*E	2761988	09/10/09	KVM	Removed obsolete parts from Ordering Information table: CY23S09ZC-1, CY23S09OC-1, CY23S09OC-1H, CY23S09ZXC-1, CY23S09OXC-1, CY23S09OXC-1H. Added CY23S05SXC-1T, CY23S05SXC-1HT, CY23S09SXC-1T, CY23S09SXC-1HT, CY23S09ZXC-1HT. Removed Status column from Ordering Information table; added footnote. Updated package names and added numerical temperature range to Ordering Information table. Removed QSOP package drawing.
*F	2897373	03/22/10	CXQ	Removed part numbers CY23S05SC-1, CY23S05SC-1H, CY23S09SC-1, CY23S09SC-1H, and CY23S09ZC-1H from Ordering Information table. Added CY23S05SXI-1 and CY23S05SXI-1T to Ordering Information table. Updated package diagrams. Updated copyright section.
*G	3394655	10/04/11	PURU	Added Figure 1 Updated Hyper links Updated Package Diagrams Added Ordering Code Definitions , Acronym , and Units of Measure .

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